







Charge Trapping Properties of 3C- and 4H-SiC MOS Capacitors with Nitrided Gate Oxide



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Objective Motivation R Introduction **experimental Results CR** Discussion

Objective A Motivation ca Introduction **c** Experimental Results **R**Discussion

Objective

- Effect of ionizing radiation on 4H- / 3C- SiC MOS capacitors.
- Charge trapping comparison of oxides with nitridation using two nitridation agents (NO, N₂O)

Experimental

Results

Discussion

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Rectric field, Bias temperature, dose dependence

Motivation Introduction

Objective

co Objective **Motivation AIntroduction CR** Experimental Results **R** Discussion

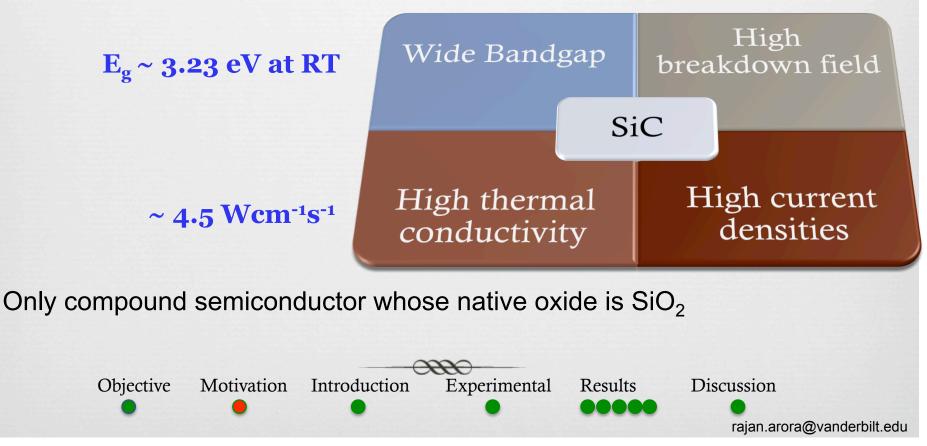
Motivation

Space missions - Electronic switches and circuits

High power and high temperature systems

Concerns: Weight, efficiency and reliability

~ 2.0 MV cm⁻¹



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Introduction

Thermal oxidation of SiC

Objective

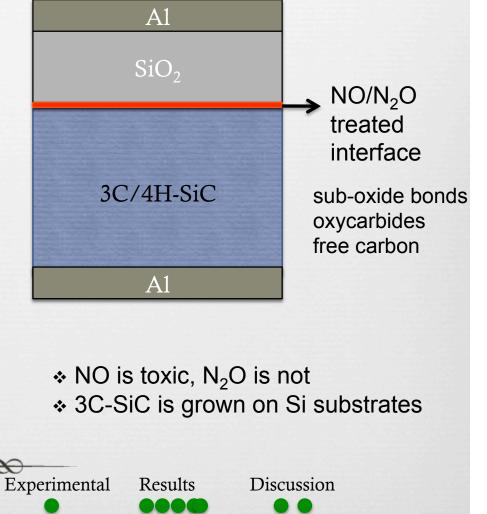
- SiO₂/SiC interface is different from SiO₂/Si
- Hydrogen treatment not effective, nitridation effective

Close to CB edge:

 $D_{it} \sim 10^{13} \text{ cm}^{-2} \text{ eV}^{-1} \text{ ---> as-oxidized}$ $D_{it} \sim 10^{12} \text{ cm}^{-2} \text{ eV}^{-1} \text{ ---> nitrided}$

> Energy band diagram of Si, SiC polytypes and SiO₂ $\begin{array}{c}
> E_{c} \rightarrow 3C \rightarrow 15R \rightarrow 6H \rightarrow 4H \rightarrow F_{c} \rightarrow 6eV \rightarrow F_{v} \rightarrow 2.38 \ 2.96 \ 3.02 \ 3.26 \ 8.9 \rightarrow 6eV \rightarrow F_{v} \rightarrow F_{v}$

> > Motivation Introduction



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Experimental

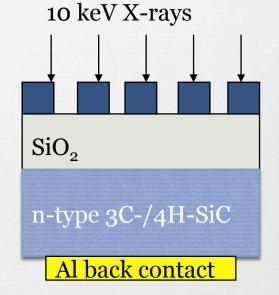
rradiation:

10 keV X-rays, RT radiation

- 31.5 krad(SiO₂)/min dose rate
- Function of dose
- Function of positive bias [~0.8 MV/cm, ~1.5 MV/cm]

Characterization:

- Stress-characterize-stress routine
- C-V, I-V, D_{it}-E

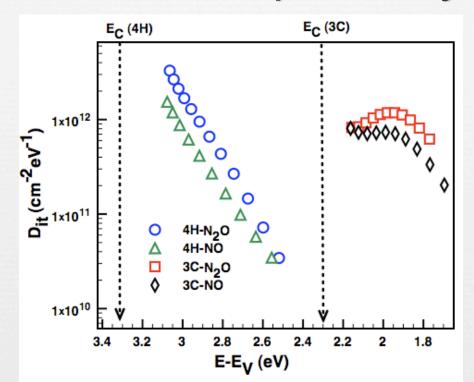




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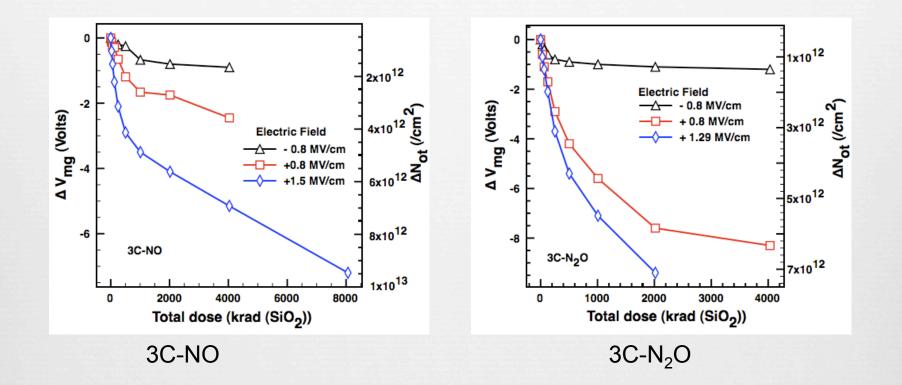
Interface trap density



 N_2O treated oxides have greater interface trap density than NO treated on both 3C- and 4H-SiC



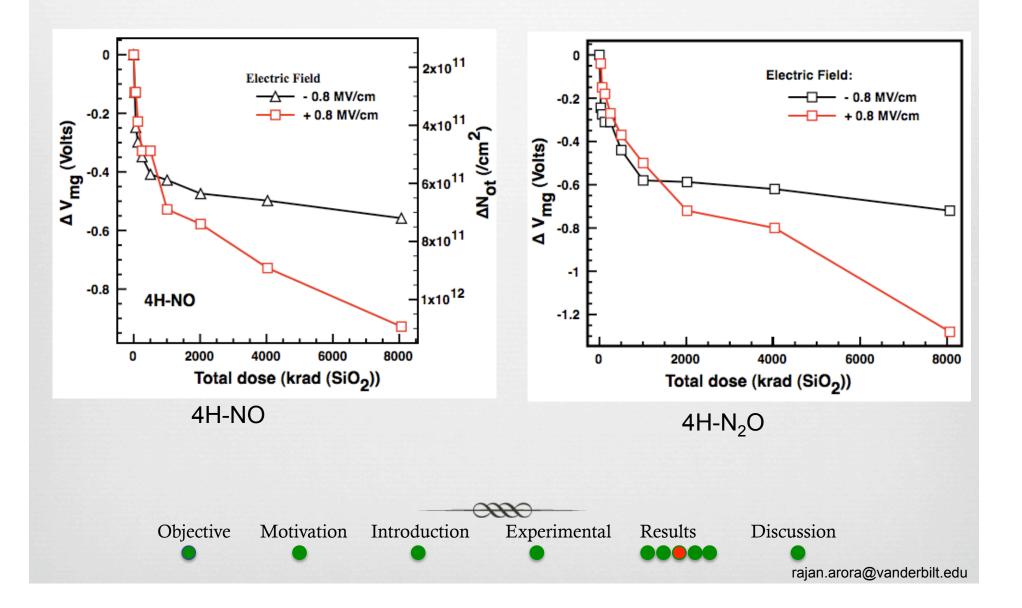
Midgap voltage shifts – 3C-SiC



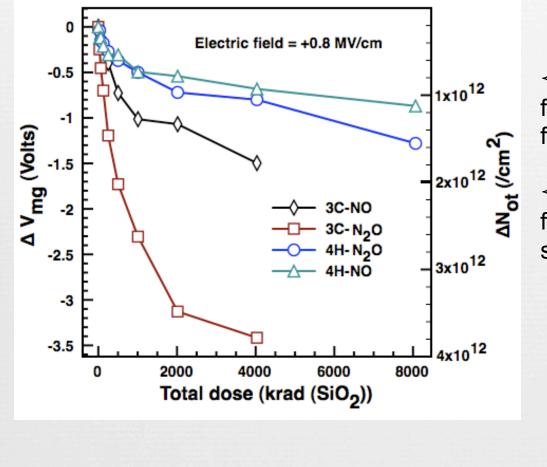
Consistent trend (a linear increase followed by saturation)



Midgap voltage shifts – 4H-SiC



Comparison

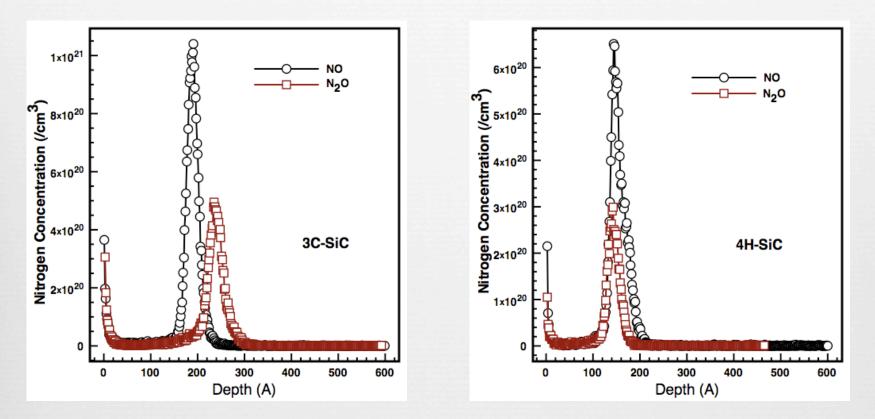


 \diamond Greater charge trapping for N₂O treated oxide than for NO treatment.

 ♦ Greater charge trapping for 3C- than 4H-SiC substrate



Nitrogen SIMS profiles



NO treated oxides deposit greater nitrogen content at the SiO₂-SiC interface for both 3C- and 4H-SiC MOS capacitors.



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Mechanisms

♦Why nitridation helps in decreasing interface/ oxide trap densities:

 creates strong SiEN bond that passivates interface traps due to dangling and strained bonds

• passivates carbon related interface traps, removes interstitial carbon and complex silicon-oxycarbon bonds

 \diamond Mechanism behind greater charge trapping for N₂O treated oxides:

 more efficient removal of interfacial carbon clusters for NO as compared to N₂O

• N₂O upon dissociation creates O₂ which generates additional carbon.



Conclusions

- \bigcirc NO treatments deposits greater nitrogen content at SiO₂-SiC interface then the N₂O treatment.